## Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

(Canceled) 1.-2. 3. (Currently Amended) The An anisotropically conductive adhesive according to Claim 1, comprising: conductive particles each having a plurality of crushable microcapsules that adhere to a surface of the conductive particles, wherein each microcapsule encloses a first substance; and a second substance that is curable by a reaction with the first substance, the conductive particles are dispersed in the second substance; wherein the first substance being any substance or mixture of is selected from the group consisting of amines, imidazoles, acid anhydrides, and phenols and mixtures thereof; and the second substance being is an uncured epoxy resin. 4. (Currently Amended) The An anisotropically conductive adhesive according to Claim 1, comprising: conductive particles each having a plurality of crushable microcapsules that adhere to a surface of the conductive particles, wherein each microcapsule encloses a first substance; and a second substance that is curable by a reaction with the first substance, the conductive particles are dispersed in the second substance;

wherein the first substance being is an uncured epoxy resin; and
the second substance being any substance or mixture of is selected from the
group consisting of amines, imidazoles, acid anhydrides, and phenols and mixtures thereof.

- 5. (Currently Amended) The anisotropically conductive adhesive according to Claim 1 Claim 3, capsule walls of the microcapsules comprising a thermoplastic resin.
  - 6. 17 (Canceled)
- 18. (Currently Amended) The anisotropically conductive adhesive according to Claim 1 Claim 3, wherein the second substance contains a third substance that is curable by a reaction with the second substance, the reaction occurring by heating

the third substance being any substance or mixture of is selected from the group consisting of imidazoles, acid anhydrides, and phenols and mixtures thereof.

19. (Currently Amended) The anisotropically conductive adhesive according to Claim 2 Claim 4, wherein the second substrate contains a third substance that is curable by a reaction with the second substance, the reaction occurring by heating,

the third substance being any substance or mixture of is selected from the group consisting of imidazoles, acid anhydrides, and phenols and mixtures thereof.